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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Mario MERLIN, et al.

Serial No.: 10/057,399

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Examiner: J. M. Mitchell

For:

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Assistant Commissioner for Patents Washington, D.C. 20231

SUBMISSION

Sir:

Submitted herewith is a copy of art together with a form listing the same for the convenience of the Examiner.

I respectfully request that the information submitted be considered and enclose our check number 14633 in payment of the required \$180.00 fee.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee due during the pendency of this application is not paid, the Patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on December 26, 2002:

Kourosh Salehi
Name of applicant, assignee or
Registered Representative

Signature
December 26, 2002

Date of Signature

Respectfully submitted,

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